## EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

PUBLICATION NUMBER

03291991

**PUBLICATION DATE** 

24-12-91

APPLICATION DATE

09-04-90

APPLICATION NUMBER

02093529

APPLICANT: FUJITSU LTD;

INVENTOR: MORIIZUMI KIYOKAZU;

INT.CL.

: H05K 3/24 H05K 3/34

TITLE

: FORMING METHOD FOR PAD

4第2の覃膜 5半田 3年1の草膜 2A侧面 ·IA上面 2 里图图 基板

6 パッド

ABSTRACT: PURPOSE: To form a stable pad and to improve reliability by laminating a first thin film and a second thin film on a conductive layer formed on a substrate, and fusion-bonding solder on the upper layer of the second film.

> CONSTITUTION: A first thin film 3 of nickel plating is so laminated as to cover a conductive layer 2 having a thickness (t) to be formed in a predetermined shape on the surface 1A of a substrate 1, and a second thin film 4 is further so laminated by gold plating as to cover the film 3 to form a pad 6. Solder 5 to be fusion-bonded on the pad 6 is secured on the upper layer 4A of the film 4 so that the layer 2 is not brought into direct contact with the solder 5.

COPYRIGHT: (C)1991,JPO&Japio